ABSTRACT OF THE DISCLOSURE

A method of machining a glass substrate by using a laser, in which a low-permittivity, low-dielectric-loss glass substrate capable of coping with mass production processes is made applicable as the substrate of a high-frequency circuit intended for microwave and millimeter-wave bands in particular. For that purpose, a glass substrate is provided in which the amount of air bubbles in glass is arbitrarily controlled to improve the workability of the substrate itself. Then, the glass substrate is machined while being irradiated with a pulsed laser for a plurality of times, thereby improving the machining shape of the glass substrate. Since glass substrates which are typically difficult to machine can be easily applied to the fabrication of high-frequency circuits, it becomes possible to supply high-performance circuits and apparatuses widely to the public.